



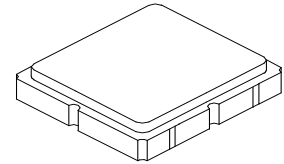
AEC-Q200
This component was always
RoHS compliant from the first
date of manufacture.

- Low Loss RF SAW Filter
- Surface Mount 3.0 x 3.0 mm Package
- Complies with Directive 2002/95/EC (RoHS)



SF2293E

**1561 MHz
SAW Filter**



SM3030-6

Absolute Maximum Ratings

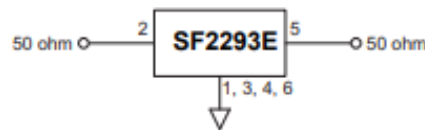
Rating	Value	Units
Input Power Level	10	dBm
DC Voltage on any Non-ground Terminal	3	V
Operable Temperature Range	-45 to +125	°C
Specification Temperature Range	-40 to +85	°C
Storage Temperature Range	-40 to +95	°C
Suitable for Lead-free Soldering - Maximum Soldering Profile	260 °C for 30 s	

Electrical Characteristics

Characteristic	Sym	Notes	Min	Typ	Max	Units
Center Frequency	f_C			1561		MHz
Insertion Loss, 1550.5 to 1571.5 MHz	IL			3.3	4.0	dB
Amplitude Ripple, 1550.5 to 1571.5 MHz				0.5	2.0	
Input/Output VSWR, 1550.5 to 1571.5 MHz				1.5:1	2:1	
Attenuation, Referenced to 0 dB:						dB
$f_C - 500$ to $f_C - 100$ MHz			45	49		
$f_C - 100$ to $f_C - 60$ MHz			40	45		
$f_C - 60$ to $f_C - 40$ MHz, -40 to +70 °C			20	32.5		
$f_C - 60$ to $f_C - 40$ MHz, -40 to +85 °C			15	32.5		
$f_C + 40$ to $f_C + 60$ MHz			20	26		
$f_C + 60$ to $f_C + 80$ MHz			35	43		
$f_C + 80$ to $f_C + 500$ MHz			45	50		
Source Impedance	Z_S			50		Ω
Load Impedance	Z_L			50		
Case Style	SM3030-6 3.0 x 3.0 mm Nominal Footprint					
Lid Symbolization (Y=year, WW=week, S=shift) dot=pin 1 indicator	A45, YWWS					
Standard Reel Quantity	Reel Size 7 Inch	500 Pieces/Reel				
	Reel Size 13 Inch	3000 Pieces/Reel				

Electrical Connections

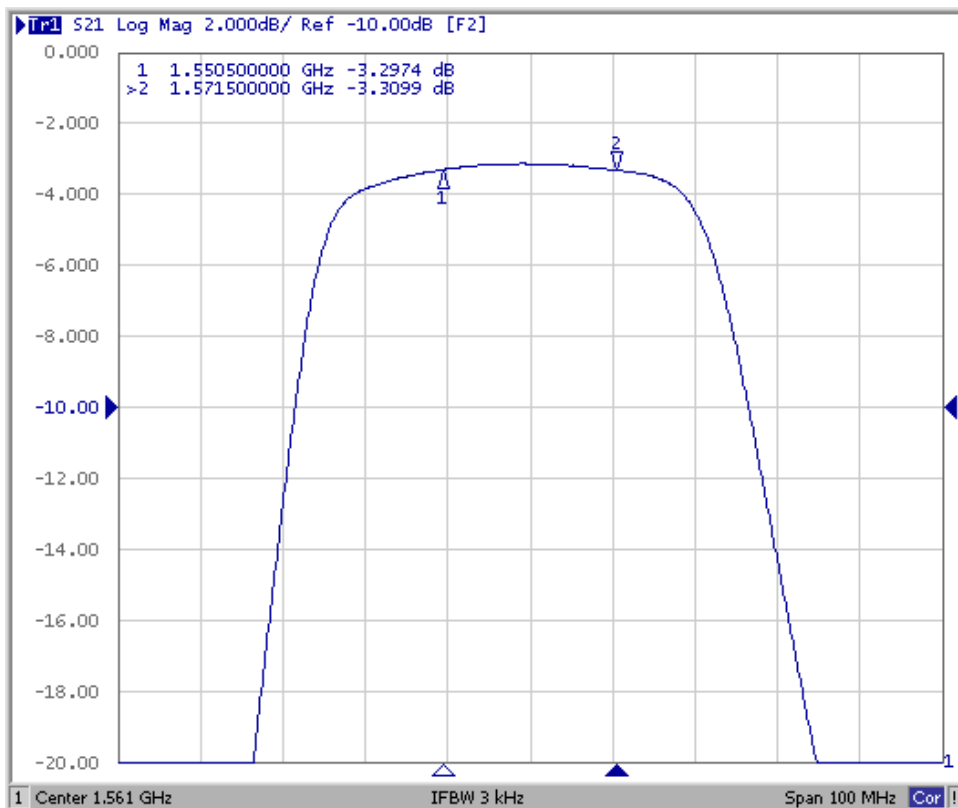
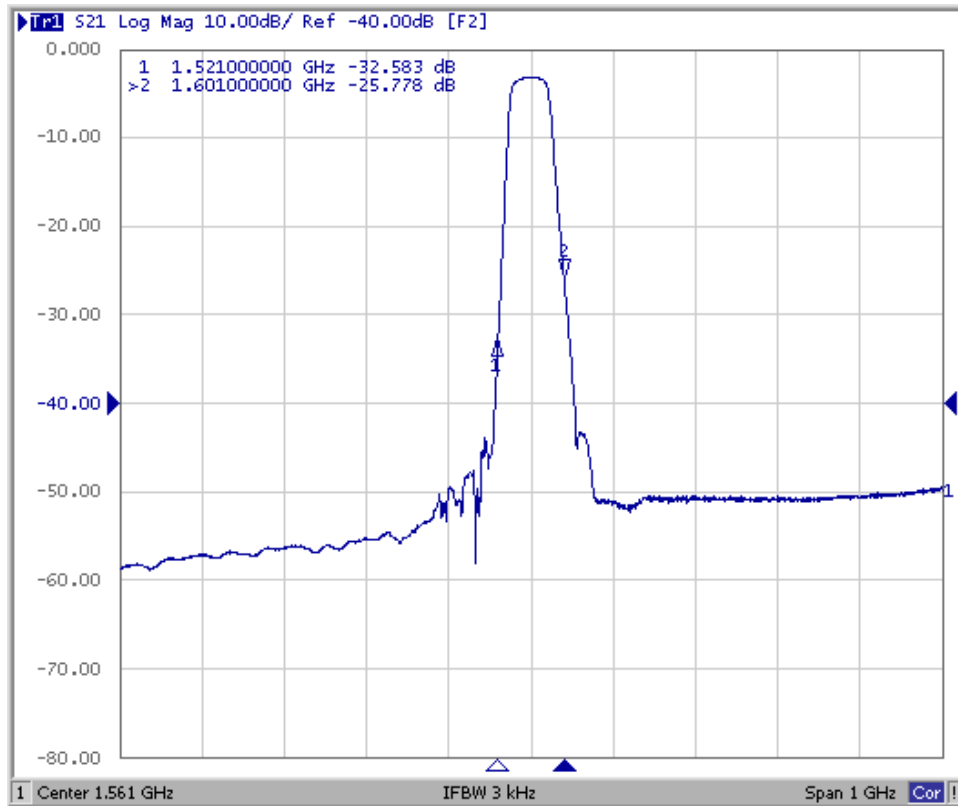
Connection	Terminals
Input	2
Output	5
Case Ground	All others



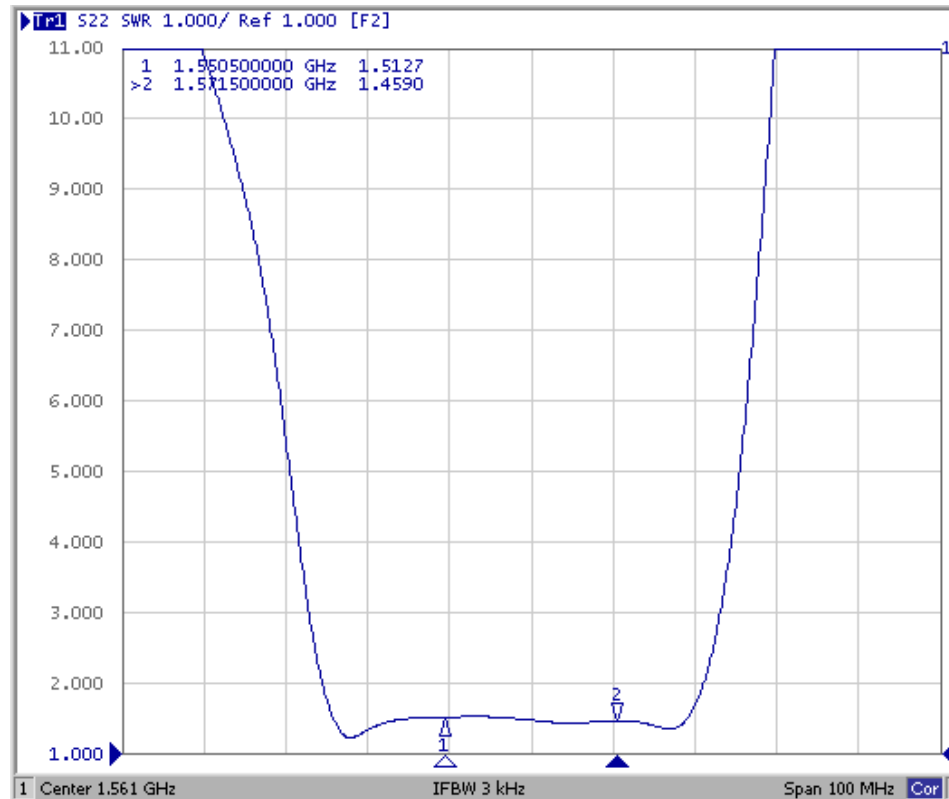
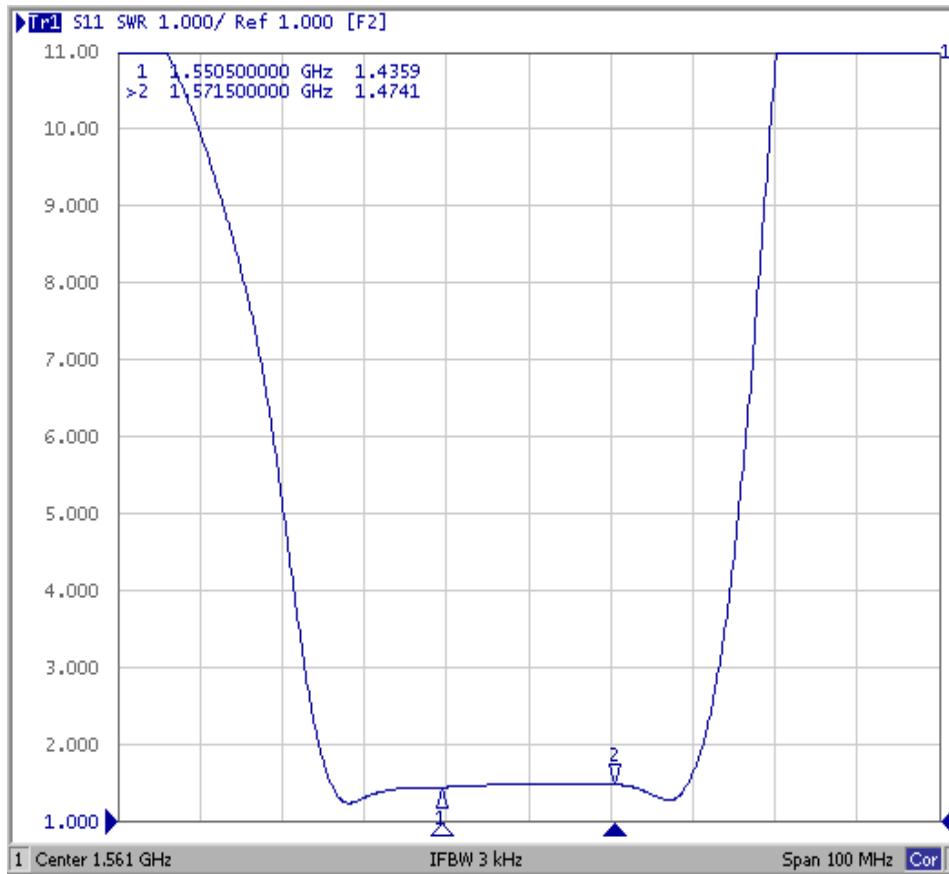
CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.
NOTES:

1. The design, manufacturing process, and specifications of this device are subject to change.
2. US or International patents may apply.

Filter Response Plots



Filter VSWR Plots



SM3030-6 Case

6-Terminal Ceramic Surface-Mount Case 3.0 X 3.0 mm Nominal Footprint



PCB Footprint Top View

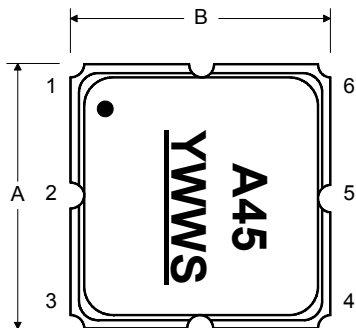
Case and PCB Footprint Dimensions

Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	2.87	3.00	3.13	0.113	0.118	0.123
B	2.87	3.00	3.13	0.113	0.118	0.123
C	1.12	1.25	1.38	0.044	0.049	0.054
D	0.77	0.90	1.03	0.030	0.035	0.040
E	2.67	2.80	2.93	0.105	0.110	0.115
F	1.47	1.60	1.73	0.058	0.063	0.068
G	0.72	0.85	0.98	0.028	0.033	0.038
H	1.37	1.50	1.63	0.054	0.059	0.064
I	0.47	0.60	0.73	0.019	0.024	0.029
J	1.17	1.30	1.43	0.046	0.051	0.056
K		3.20			0.126	
L		1.70			0.067	
M		1.05			0.041	
N		0.81			0.032	
O		0.38			0.015	

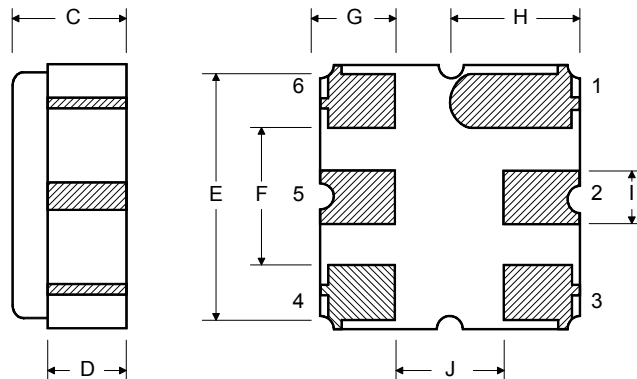
Case Materials

Materials	
Solder Pad Plating	0.3 to 1.0 μm Gold over 1.27 to 8.89 μm Nickel
Lid Plating	2.0 to 3.0 μm Nickel
Body	Al_2O_3 Ceramic
Pb Free	

TOP VIEW

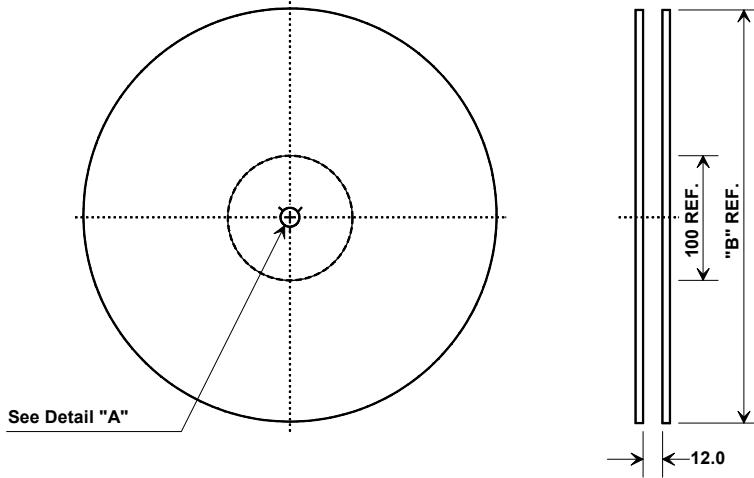


BOTTOM VIEW

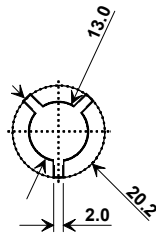


Tape and Reel Specifications

Tape and Reel Standard per ANSI/EIA-481

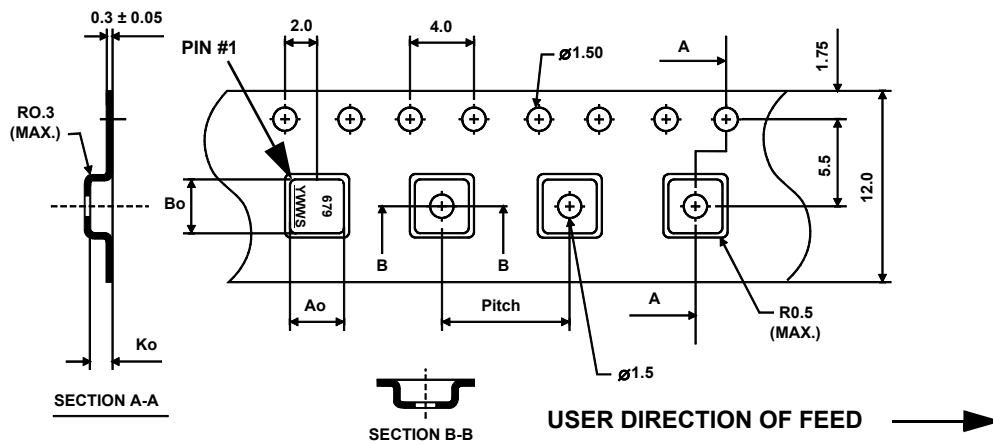


"B"		Quantity Per Reel
Inches	millimeters	
7	178	500
13	330	3000



COMPONENT ORIENTATION and DIMENSIONS

Carrier Tape Dimensions	
Ao	3.35 mm
Bo	3.35 mm
Ko	1.40 mm
Pitch	8.0 mm
W	12.0 mm



Recommended Reflow Profile

1. Preheating shall be fixed at 150~180°C for 60~90 seconds.
2. Ascending time to preheating temperature 150°C shall be 30 seconds min.
3. Heating shall be fixed at 220°C for 50~80 seconds and at 260°C +0/-5°C peak (10 seconds).
4. Time: 5 times maximum.

